

TOSHIBA Field Effect Transistor Silicon P Channel MOS Type ( $L^2$ - $\pi$ -MOSIV)

## 2SJ304

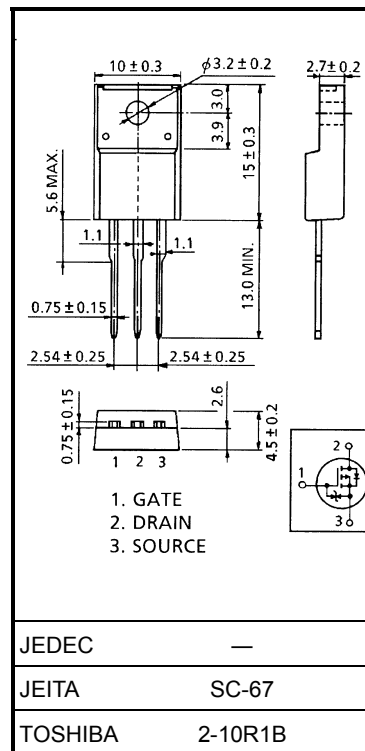
DC-DC Converter, Relay Drive and Motor Drive Applications

Unit: mm

- 4-V gate drive
- Low drain-source ON resistance :  $R_{DS(ON)} = 80 \text{ m}\Omega$  (typ.)
- High forward transfer admittance :  $|Y_{fs}| = 8.0 \text{ S}$  (typ.)
- Low leakage current :  $I_{DSS} = -100 \text{ }\mu\text{A}$  (max) ( $V_{DS} = -60 \text{ V}$ )
- Enhancement mode :  $V_{th} = -0.8 \sim -2.0 \text{ V}$  ( $V_{DS} = -10 \text{ V}$ ,  $I_D = -1 \text{ mA}$ )

Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

Characteristics		Symbol	Rating	Unit
Drain-source voltage		$V_{DSS}$	-60	V
Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ )		$V_{DGR}$	-60	V
Gate-source voltage		$V_{GSS}$	$\pm 20$	V
Drain current	DC (Note 1)	$I_D$	-14	A
	Pulse (Note 1)	$I_{DP}$	-56	
Drain power dissipation ( $T_c = 25^\circ\text{C}$ )		$P_D$	40	W
Channel temperature		$T_{ch}$	150	$^\circ\text{C}$
Storage temperature range		$T_{stg}$	-55~150	$^\circ\text{C}$



Weight: 1.9 g (typ.)

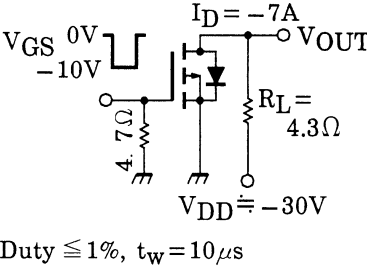
## Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th(ch-c)}$	3.125	$^\circ\text{C} / \text{W}$
Thermal resistance, channel to ambient	$R_{th(ch-a)}$	62.5	$^\circ\text{C} / \text{W}$

Note 1: Ensure that the channel temperature does not exceed  $150^\circ\text{C}$ .

This transistor is an electrostatic-sensitive device.  
Please handle with caution.

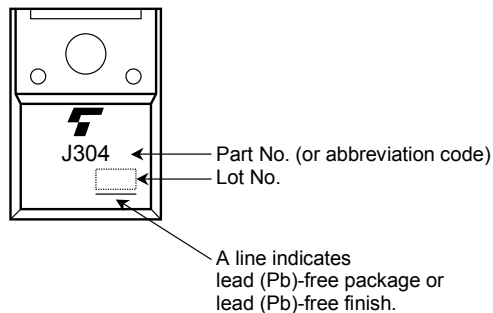
## Electrical Characteristics (Ta = 25°C)

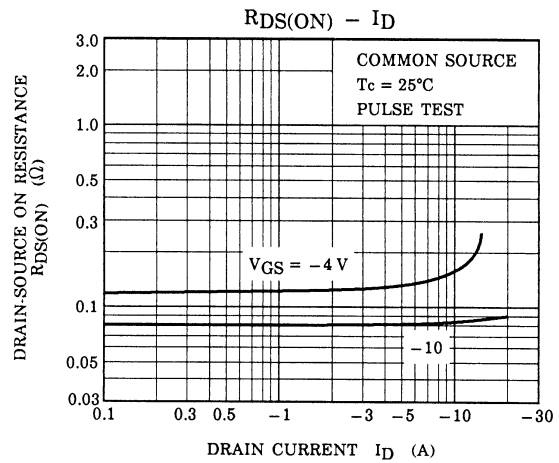
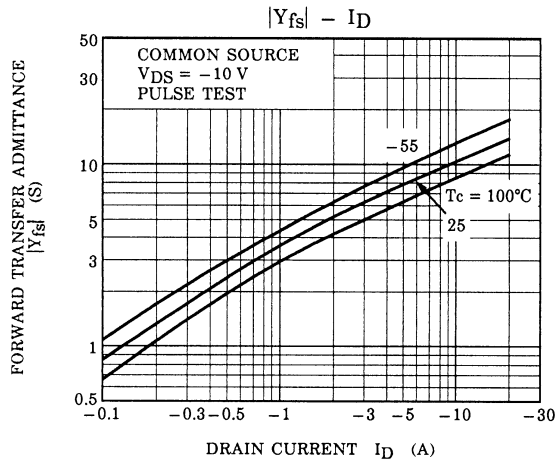
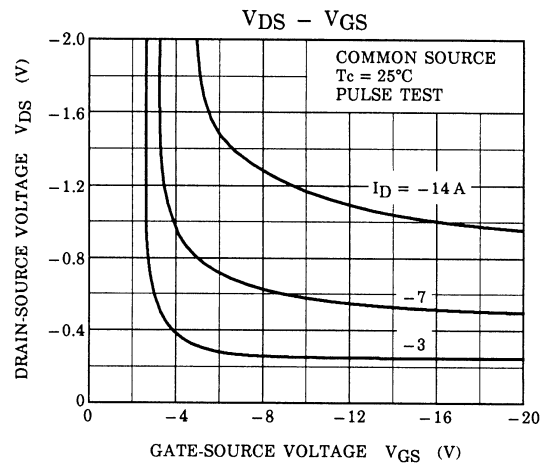
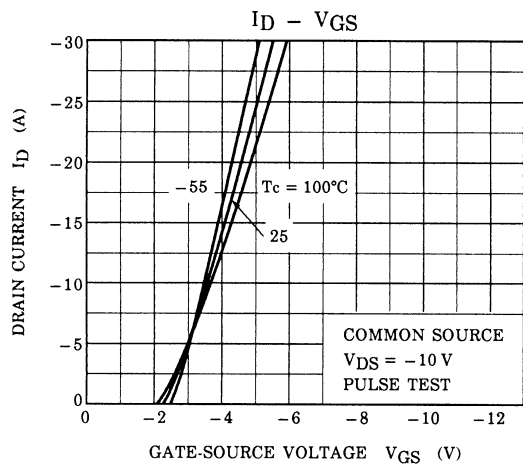
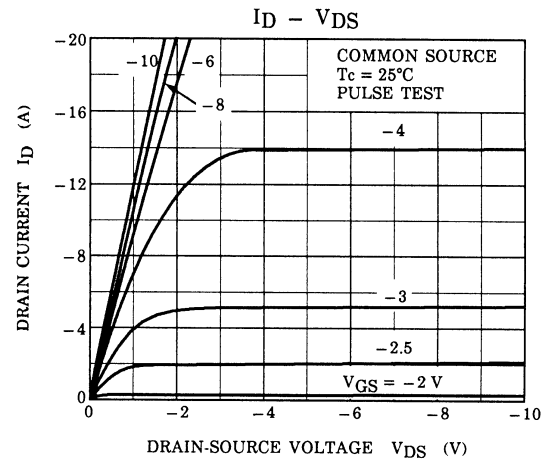
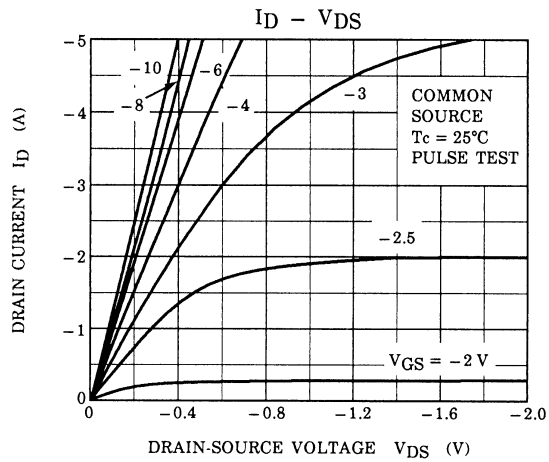
Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		$I_{GSS}$	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	—	—	$\pm 10$	$\mu\text{A}$
Drain cut-off current		$I_{DSS}$	$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}$	—	—	-100	$\mu\text{A}$
Drain-source breakdown voltage		$V_{(BR)DSS}$	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-60	—	—	V
Gate threshold voltage		$V_{th}$	$V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}$	-0.8	—	-2.0	V
Drain-source ON resistance		$R_{DS(ON)}$	$V_{GS} = -4 \text{ V}, I_D = -5 \text{ A}$	—	130	190	m $\Omega$
			$V_{GS} = -10 \text{ V}, I_D = -7 \text{ A}$	—	80	120	
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = -10 \text{ V}, I_D = -7 \text{ A}$	5.0	8.0	—	S
Input capacitance		$C_{iss}$	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	—	1200	—	pF
Reverse transfer capacitance		$C_{rss}$		—	220	—	
Output capacitance		$C_{oss}$		—	550	—	
Switching time	Rise time	$t_r$		—	20	—	ns
	Turn-on time	$t_{on}$		—	30	—	
	Fall time	$t_f$		—	25	—	
	Turn-off time	$t_{off}$		—	100	—	
Total gate charge (Gate-source plus gate-drain)		$Q_g$	$V_{DD} \approx -48 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -14 \text{ A}$	—	45	—	nC
Gate-source charge		$Q_{gs}$		—	30	—	
Gate-drain ("miller") charge		$Q_{gd}$		—	15	—	

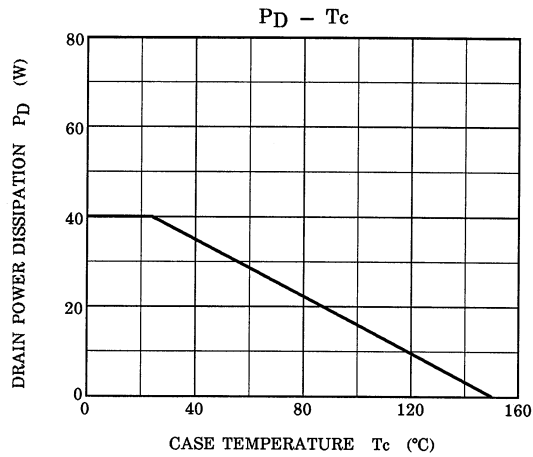
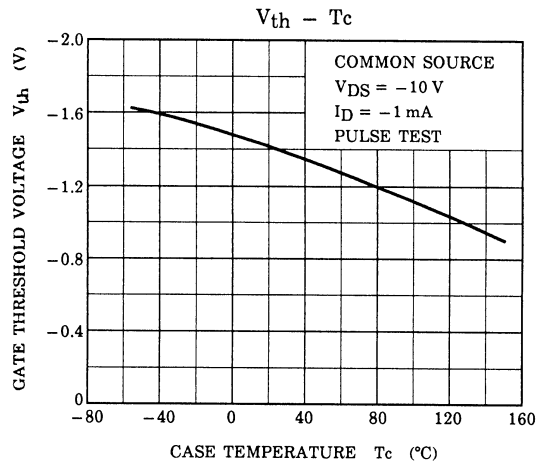
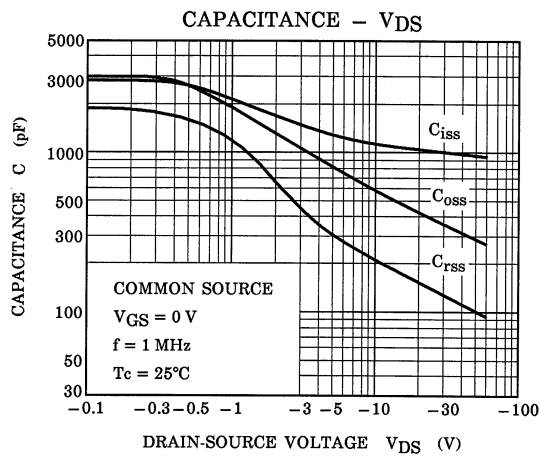
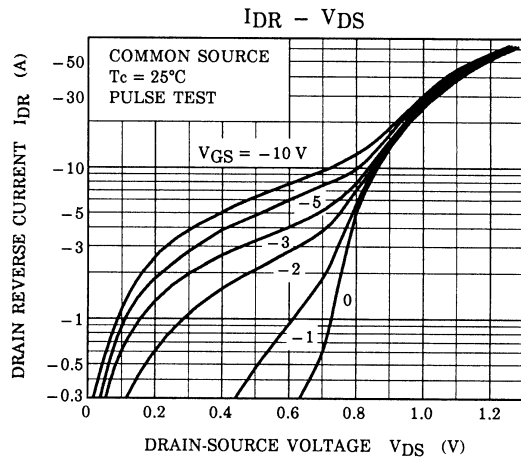
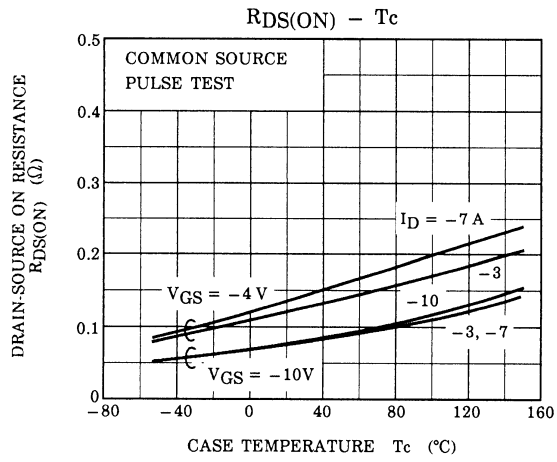
## Source-Drain Ratings and Characteristics (Ta = 25°C)

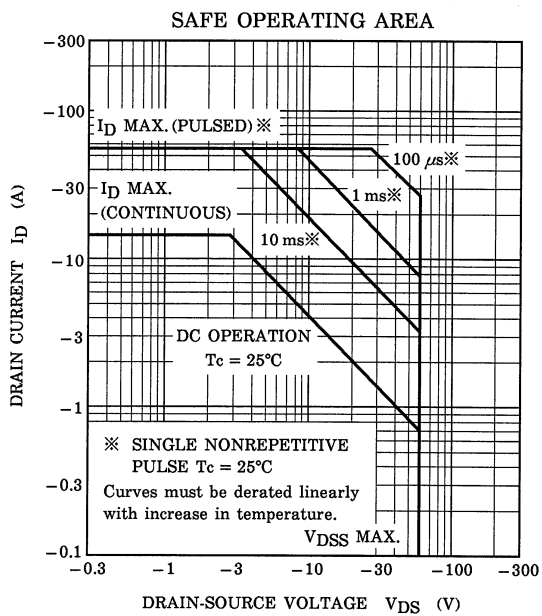
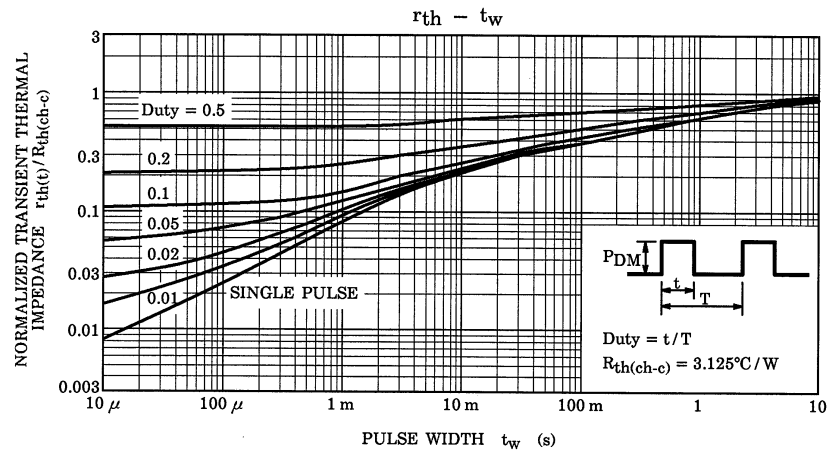
Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	$I_{DR}$	—	—	—	-14	A
Pulse drain reverse current (Note 1)	$I_{DRP}$	—	—	—	-56	A
Forward voltage (diode)	$V_{DSF}$	$I_{DR} = -14 \text{ A}, V_{GS} = 0 \text{ V}$	—	—	1.7	V
Reverse recovery time	$t_{rr}$	$I_{DR} = -14 \text{ A}, V_{GS} = 0 \text{ V}$	—	110	—	ns
Reverse recovery charge	$Q_{rr}$	$dI_{DR} / dt = 50 \text{ A} / \mu\text{s}$	—	0.18	—	$\mu\text{C}$

## Marking









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